

RD Number: RD059

RD Title: TB67S103AFTG Evaluation Circuit

| Item No. | Designator | Quantity | Value | Part Number | Manufacturer | Description | Package | Not Mount |
|----------|------------|----------|-----------|-----------------|-----------------|------------------------|------------------------|-----------|
| 1 | C_VCC | 1 | 0.1μF,25V | | | Chip capacitor | 3.2mmX1.6mm | |
| 2 | C_VM2 | 1 | 0.1μF,25V | | | Chip capacitor | 3.2mmX1.6mm | |
| 3 | C_VRFA | 1 | 0.1μF,25V | | | Chip capacitor | 3.2mmX1.6mm | |
| 4 | C_VRFB | 1 | 0.1μF,25V | | | Chip capacitor | 3.2mmX1.6mm | |
| 5 | C_VM1 | 1 | 100μF,50V | | | Electrolytic capacitor | YK,φDXL(mm) =8X11.5 | |
| 6 | C_VDD | 1 | 10μF,25V | | | Electrolytic capacitor | φD=8mm | |
| 7 | C_OSCM | 0 | | PD-10 | Mac8 | Socket pin | | ✓ |
| 8 | C_OSCM | 0 | 270pF,25V | 2.54mm pitch | | Leaded capacitor | | ✓ |
| 9 | C_OSCM | 1 | 270pF,25V | | | Chip capacitor | 3.2mmX1.6mm | |
| 10 | C_OAP | 0 | | | | Chip capacitor | 3.2mmX1.6mm | ✓ |
| 11 | C_OAM | 0 | | | | Chip capacitor | 3.2mmX1.6mm | ✓ |
| 12 | C_OBM | 0 | | | | Chip capacitor | 3.2mmX1.6mm | ✓ |
| 13 | C_OBP | 0 | | | | Chip capacitor | 3.2mmX1.6mm | ✓ |
| 14 | CON1 | 1 | | DF1BZ-4P-2.5DSA | Hirose Electric | Connector | | |
| 15 | CON2 | 0 | | DF1BZ-2P-2.5DSA | Hirose Electric | Connector | | ✓ |
| 16 | CON3 | 0 | | DF1BZ-2P-2.5DSA | Hirose Electric | Connector | | ✓ |
| 17 | CON4 | 0 | | DF1BZ-3P-2.5DSA | Hirose Electric | Connector | | ✓ |
| 18 | CON5 | 0 | | DF1BZ-3P-2.5DSA | Hirose Electric | Connector | | ✓ |
| 19 | OUT_A- | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 20 | OUT_A+ | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 21 | OUT_B- | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 22 | OUT_B+ | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 23 | RSA | 1 | | LC-22-G | Mac8 | Check pin | | |
| 24 | RSB | 1 | | LC-22-G | Mac8 | Check pin | | |
| 25 | VCC | 1 | | LC-22-G | Mac8 | Check pin | | |
| 26 | VDD | 1 | | LC-22-G | Mac8 | Check pin | | |

| | | | | | | | | |
|----|---------|---|------------|-------------------------|--------|-----------------|--------------|---|
| 27 | VM | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 28 | NC | 0 | | LC-22-G | Mac8 | Check pin | | ✓ |
| 29 | 38 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 30 | 39 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 31 | VREFB | 1 | | LC-22-G | Mac8 | Check pin | | |
| 32 | 42 | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 33 | OSCM | 1 | | LC-22-G | Mac8 | Check pin | | |
| 34 | 44 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 35 | 45 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 36 | 46 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 37 | 47 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 38 | 2 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 39 | 3 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 40 | 4 | 1 | | LC-22-G | Mac8 | Check pin | | |
| 41 | GND1 | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 42 | GND2 | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 43 | GND3 | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 44 | GND4 | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 45 | GND5 | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 46 | GND6 | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 47 | GND7 | 1 | | ST-1-3 | Mac8 | Check pin | | |
| 48 | JP_VRF1 | 1 | | XJ8B-0911, 2.54mm pitch | Omron | Jumper | | |
| 49 | JP_VRF1 | 1 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | |
| 50 | JP_VRF2 | 1 | | XJ8B-0911, 2.54mm pitch | Omron | Jumper | | |
| 51 | JP_VRF2 | 1 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | |
| 52 | JP_VCC | 1 | | XJ8B-0911, 2.54mm pitch | Omron | Jumper | | |
| 53 | JP_VCC | 1 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | |
| 54 | R_ID | 1 | 100kΩ,1/4W | | | Leaded resistor | 2.54mm pitch | |
| 55 | R_MOUT | 1 | 100kΩ,1/4W | | | Leaded resistor | 2.54mm pitch | |
| 56 | R_LOUT | 1 | 100kΩ,1/4W | | | Leaded resistor | 2.54mm pitch | |
| 57 | R_OSCM | 0 | | PD-10 | Mac8 | Socket pin | | ✓ |
| 58 | R_OSCM | 0 | 5.1kΩ | 2.54mm pitch | | Leaded resistor | | ✓ |
| 59 | R_OSCM | 1 | 5.1kΩ | 3.2mm×1.6mm | | Chip resistor | | |
| 60 | R_VRF1 | 2 | | PD-10 | Mac8 | Socket pin | | |

| | | | | | | | | |
|----|--------|---|----------|-------------------------|---------|-----------------|--|---|
| 61 | R_VRF1 | 0 | | 2.54mm pitch | | Leaded resistor | | ✓ |
| 62 | R_VRF2 | 2 | | PD-10 | Mac8 | Socket pin | | |
| 63 | R_VRF2 | 0 | | 2.54mm pitch | | Leaded resistor | | ✓ |
| 64 | R_RSA | 1 | 0.22Ω,1W | 5.0mm×2.5mm | | Chip resistor | | |
| 65 | R_RSB | 1 | 0.22Ω,1W | 5.0mm×2.5mm | | Chip resistor | | |
| 66 | SW2 | 0 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | ✓ |
| 67 | SW2 | 0 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | ✓ |
| 68 | SW3 | 1 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | |
| 69 | SW3 | 1 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | |
| 70 | SW4 | 1 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | |
| 71 | SW4 | 1 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | |
| 72 | SW39 | 0 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | ✓ |
| 73 | SW39 | 0 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | ✓ |
| 74 | SW42 | 0 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | ✓ |
| 75 | SW42 | 0 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | ✓ |
| 76 | SW44 | 0 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | ✓ |
| 77 | SW44 | 0 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | ✓ |
| 78 | SW45 | 0 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | ✓ |
| 79 | SW45 | 0 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | ✓ |
| 80 | SW46 | 0 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | ✓ |
| 81 | SW46 | 0 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | ✓ |
| 82 | SW47 | 0 | | XJ8B-0311, 2.54mm pitch | Omron | Jumper | | ✓ |
| 83 | SW47 | 0 | | M7567-05, 2.54mm pitch | HARWIN | Short pin | | ✓ |
| 84 | IC1 | 1 | | TB67S103AFTG | Toshiba | IC | | |

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